



#### DISCRIPTION

### **FEATURES**

Ceramic Core High frequency design Excellent Q values Excellent SRF High reliability Excellent thermal stability

## **OPTIONS**

Tape & Reel is Standard (Qty: 3.000 Pcs) Bulk Packing Available for smaller quantites Tolerance: J = 5% and K=10% is Standard, tighter Tolerance available (MOQ on request)

#### **APPLICATIONS**

Modems Mobile Radios Cordless Telephones Global Positioning Systems Telecommunications Systems

### **PHYSICAL CHARACTERISTICS**

- Testing : (Equivalents acceptable ) Inductance & Q-HP4191A + HP41951 SRF : HP8753B ; RDC : 25°C
- Operating Temperature : Ceramic -55°C ~ 125°C
- Pad metalization : Tungsten-nickel with gold flash
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

#### **ELECTRICAL SPECIFICATIONS**

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	330	nH	see Site 2
Q factor		Q	48		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	1,400	Ω	max.
Self-Res. Freq.		SRF	600	Mhz	min.
Test-Freq.			250	Mhz	
Rated Current		IDC	310	mA	max.
Saturation Current		Isat		mA	typ.

<ol> <li>This electronic component is meant to be used in general electronic equipment. Before the incorporatio of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcor</li> </ol>					h as aviation, vention, medical,	CERAMIC CHIP		
-Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability					Part No.:	S12	2003-R33	
functions.						Customer:		
DRW:	Chang	CHKD	Young	MATL:	Chu Chi	DATE		09.06.2009
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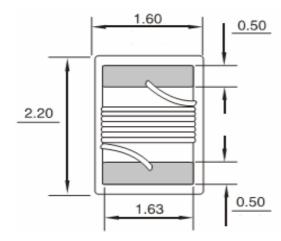
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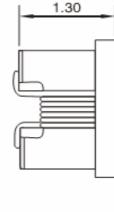


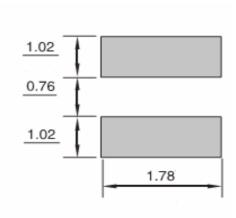


#### **TECHNICAL INFORMATIONS**

#### Dimensions (mm)





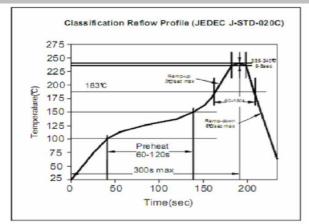


**Ordering Information** 

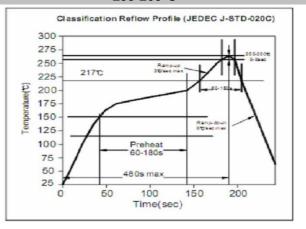
Serie and Range S12003-R33

Tolerance	ROHS	Packing
K	R	TR
<b>J</b> = 5%	<b>R =</b> ROHS	BU = Bulk Ware
<b>K</b> = 10%	N = non ROHS	TR = Tape Reel
<b>M</b> = 20%		
<b>N</b> = 30%		

# Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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